



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)}	I _D @T _A = +25°C
Q1	20V	0.45Ω @ $V_{GS} = 4.5V$	1066mA
Q2	-20V	0.75Ω @ V _{GS} = -4.5V	-845mA

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Power Supply Converter Circuits

Features and Benefits

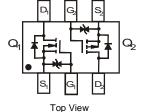
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208³
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)







Internal Schematic

Ordering Information (Note 5)

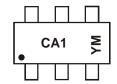
Part Number	Compliance	Case	Packaging	
DMG1016UDW-7	Standard	SOT363	3000/Tape & Reel	
DMG1016UDWQ-7	Automotive	SOT363	3000/Tape & Reel	

Top View

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



 $\begin{array}{l} \text{CA1} = \underbrace{P\text{roduct Type Marking Code}} \\ \text{YM or } \overline{\text{Y}} \text{M= Date Code Marking} \\ \text{Y or } \overline{\text{Y}} = \text{Year (ex: F = 2018)} \\ \text{M = Month (ex: 9 = September)} \end{array}$

Date Code Key

Year	2008	20	09	2010	~	20)18	2019	2020	20	21	2022
Code	V	V	V	Χ	~		F	G	Н			J
Month	lan	Eob	Mar	Anr	May	lun	11	Aug	Son	Oct	Nov	Doc



Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P _D	330	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ hetaJA}$	379	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	20	V	
Gate-Source Voltage	V _{GSS}	±6	V		
Continuous Drain Current (Note 6)			I _D	1066 690	mA
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	o)	I _{DM}	3.2	А	

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	-20	V	
Gate-Source Voltage	V _{GSS}	±6	V		
Continuous Drain Current (Note 6)	Steady State	T _A = +25°C T _A = +85°C	I _D	-845 -548	mA
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	5)	I _{DM}	-2.2	А	

Electrical Characteristics N-CHANNEL - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic		Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	•			•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current @T _C = +25°C		_	_	100	nA	V _{DS} =20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
			0.3	0.45		$V_{GS} = 4.5V, I_D = 600mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_ [0.4	0.6	Ω	$V_{GS} = 2.5V, I_D = 500mA$	
			0.5	0.75		$V_{GS} = 1.8V, I_D = 350mA$	
Forward Transfer Admittance	Y _{fs}	_	1.4	_	S	$V_{DS} = 10V, I_D = 400mA$	
Diode Forward Voltage (Note 7)		_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	60.67	_	pF		
Output Capacitance	Coss	_	9.68	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	5.37	_	pF	1 = 1.0WHZ	
Total Gate Charge	Qg	_	736.6	_	nC		
Gate-Source Charge	Qgs	_	93.6	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$	
Gate-Drain Charge	Q_{gd}	_	116.6	_	nC	$I_D = 250 \text{mA}$	
Turn-On Delay Time		_	5.1	_	ns		
Turn-On Rise Time		_	7.4	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time		_	26.7	_	ns	$R_L = 47\Omega$, $R_G = 10\Omega$	
Turn-Off Fall Time		_	12.3	_	ns		

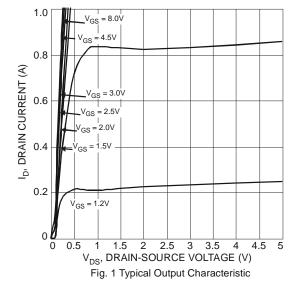
Notes: 6. Device mounted on FR-4 PCB with minimum recommended pad layout.

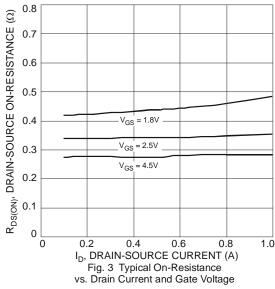
^{7.} Short duration pulse test used to minimize self-heating effect.

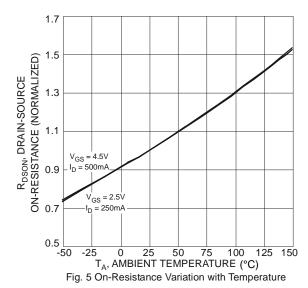
^{8.} Guaranteed by design. Not subject to production testing.

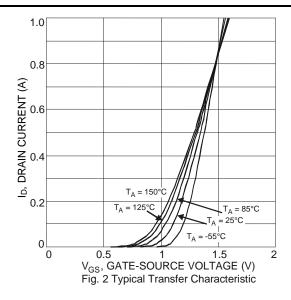


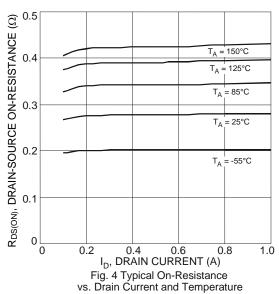
N-CHANNEL - Q1

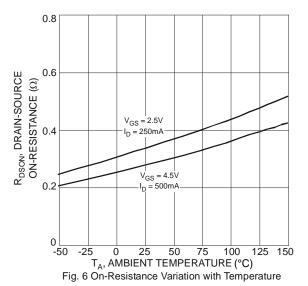






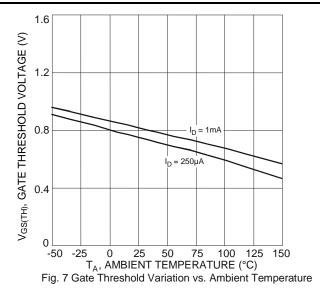


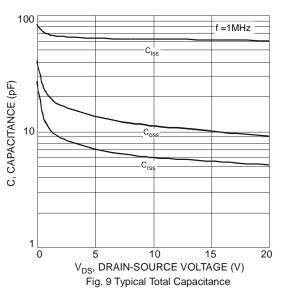


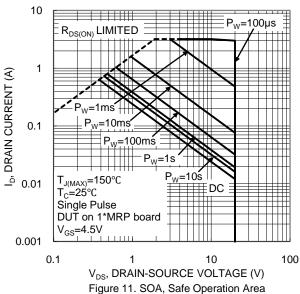


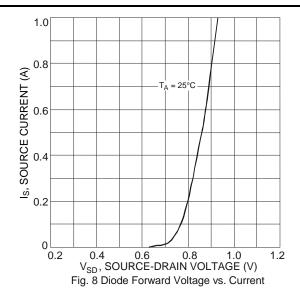


N-CHANNEL - Q1 (Cont.)









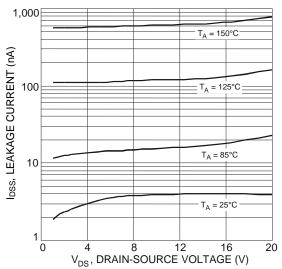
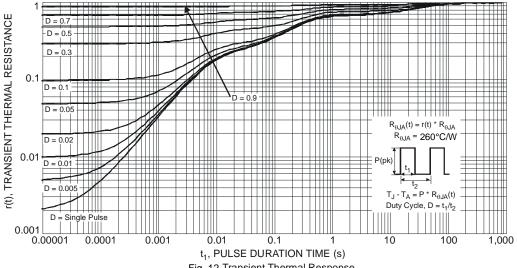


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage







Electrical Characteristics P-CHANNEL - Q2 (@T_A = +25°C, unless otherwise specified.)

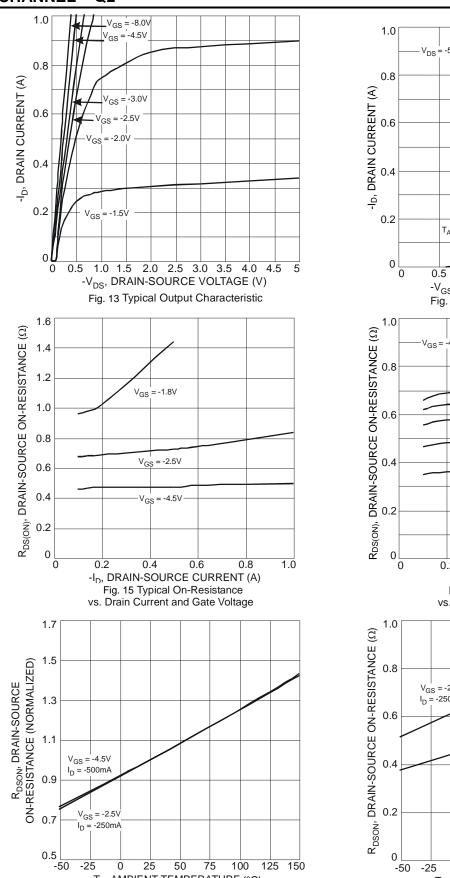
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	1	_	-100	nA	$V_{DS} = -20V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±2.0	μΑ	$V_{GS} = \pm 4.5 V, V_{DS} = 0 V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
			0.5	0.75		$V_{GS} = -4.5V, I_D = -430mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_ [0.7	1.05	Ω	$V_{GS} = -2.5V, I_D = -300mA$	
			1.0	1.5		V _{GS} = -1.8V, I _D = -150mA	
Forward Transfer Admittance	Y _{fs}	_	0.9	_	S	$V_{DS} = -10V, I_{D} = -250mA$	
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.8	-1.2	V	V _{GS} = 0V, I _S = -150mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	59.76	_	pF		
Output Capacitance	Coss	_	12.07	_	pF	$V_{DS} = -16V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	6.36	_	pF	1 = 1.000112	
Total Gate Charge	Qg	_	622.4	_	рС		
Gate-Source Charge	Q _{gs}	_	100.3	_	рС	$V_{GS} = -4.5V, V_{DS} = -10V,$	
Gate-Drain Charge	Q_{gd}	-	132.2	_	рС	$I_D = -250 \text{mA}$	
Turn-On Delay Time	t _{D(ON)}	_	5.1	_	ns		
Turn-On Rise Time		_	8.1	_	ns	$V_{DS} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time		_	28.4	_	ns	$R_G = 10\Omega, R_L = 47\Omega$	
Turn-Off Fall Time	t _F	_	20.72	_	ns		

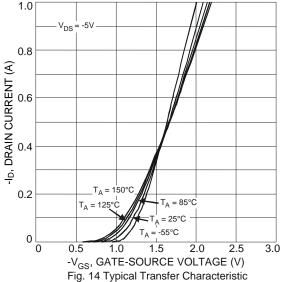
Notes:

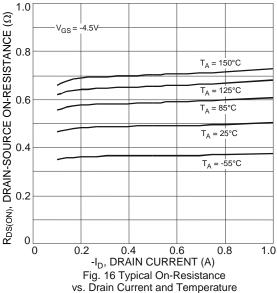
^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing

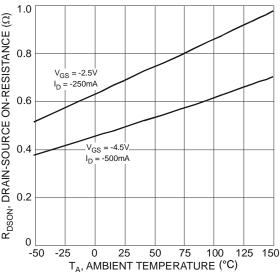


P-CHANNEL - Q2









T_A, AMBIENT TEMPERATURE (°C)

Fig. 17 On-Resistance Variation with Temperature



P-CHANNEL - Q2 (Cont.)

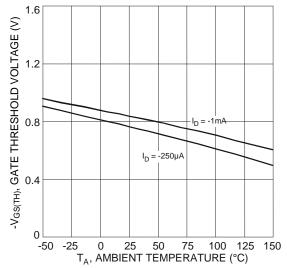
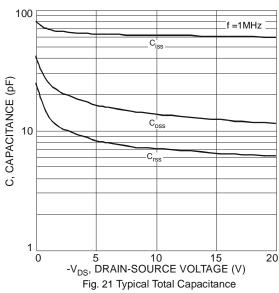
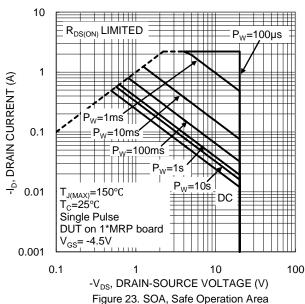
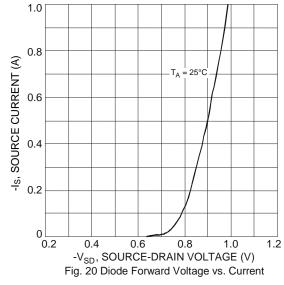
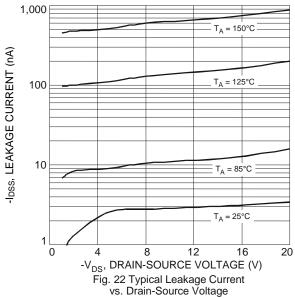


Fig. 19 Gate Threshold Variation vs. Ambient Temperature











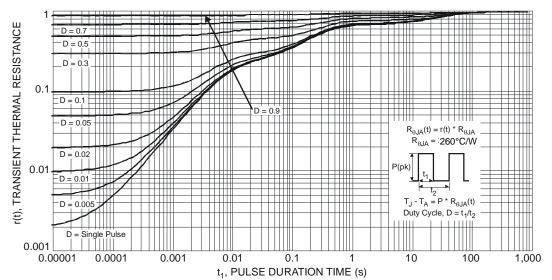


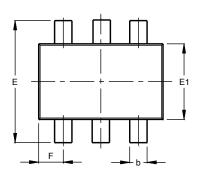
Fig. 24 Transient Thermal Response

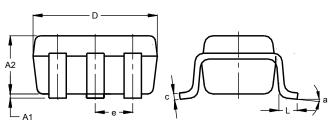


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



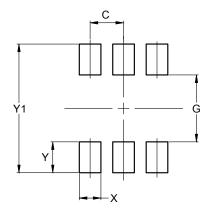


	SOT363						
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.10	0.30	0.25				
С	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C	.650 E	SC				
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All I	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



Dimensions	Value (in mm)
С	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500



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